

Modeling of Infineon BFP740 using
HICUM level 0v1.2
in QUCS 0.0.15

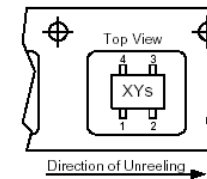
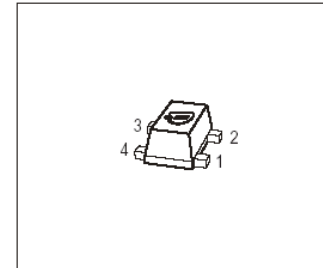
- why QUCS ?
- thermal impedance
- dc
- s-parameter
- noise
- discussion



BFP740F

NPN Silicon Germanium RF Transistor

- High gain ultra low noise RF transistor
- Provides outstanding performance for a wide range of wireless applications up to 10 GHz and more
- Ideal for CDMA and WLAN applications
- Outstanding noise figure $F = 0.5$ dB at 1.8 GHz
Outstanding noise figure $F = 0.75$ dB at 6 GHz
- High maximum stable gain
 $G_{ms} = 27.5$ dB at 1.8 GHz
- Gold metallization for extra high reliability
- 150 GHz f_T -Silicon Germanium technology
- Pb-free (RoHS compliant) package ¹⁾
- Qualified according AEC Q101

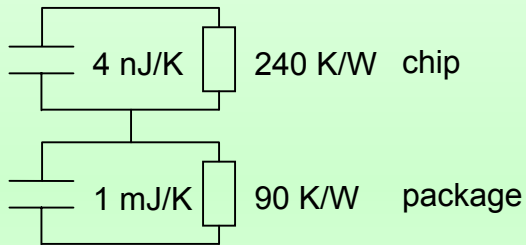


ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration						Package
BFP740F	R7s	1=B	2=E	3=C	4=E	-	-	TSFP-4

$I_c = 4 \text{ mA}$, $V_c = 1.9 \text{ V}$, time 100 ns ... 100 s, $T = 24 \text{ }^\circ\text{C}$

two-pole thermal RC-network

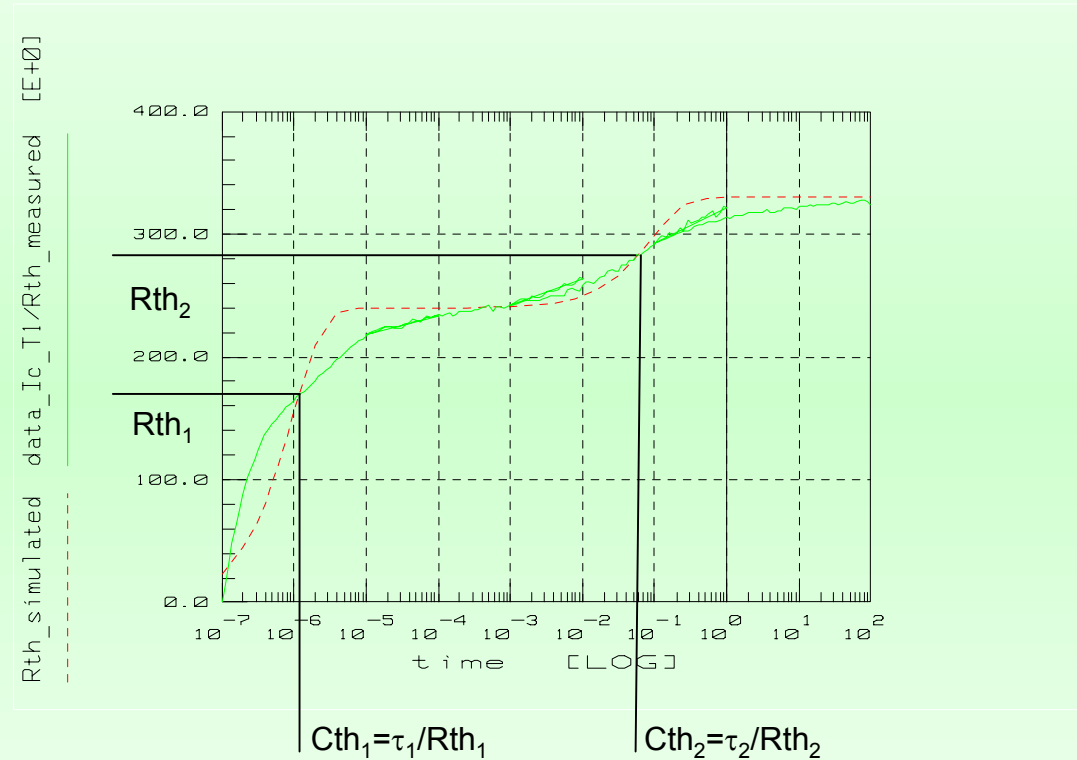


Data sheet value

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R_{thJS}	≤ 370	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified



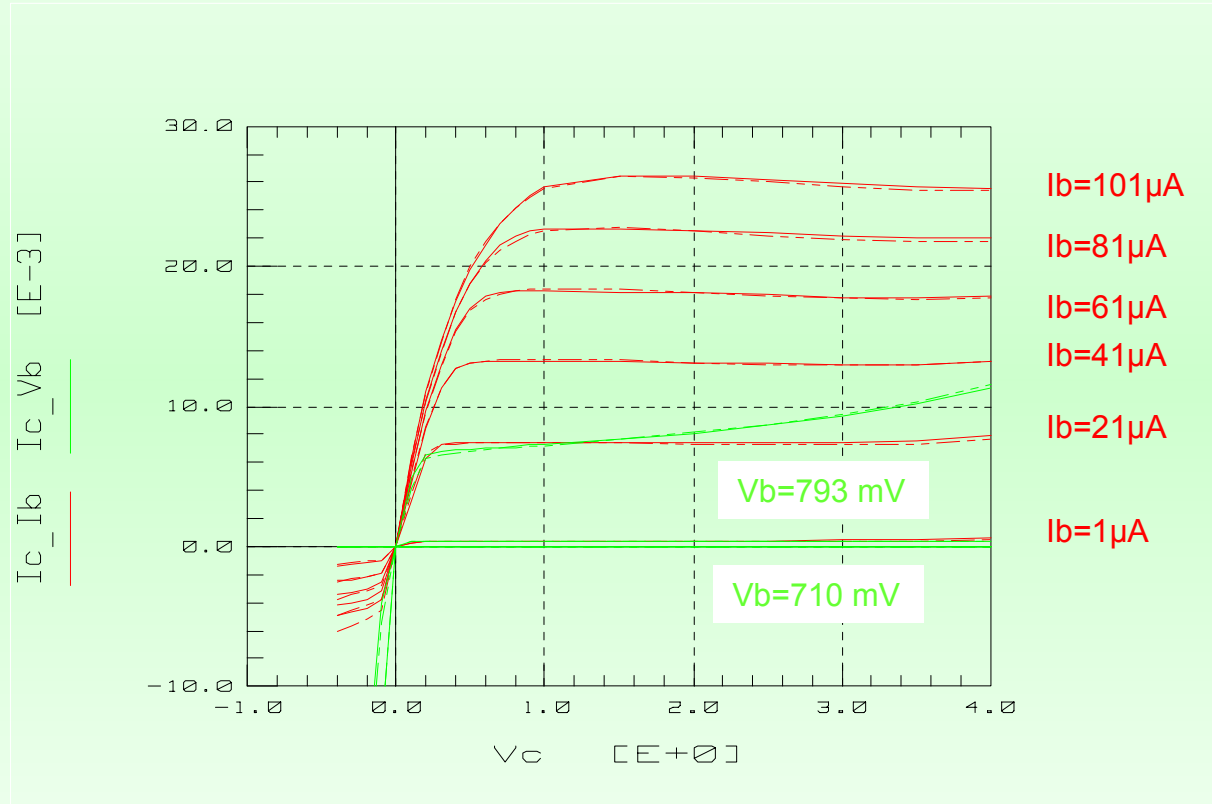
measured and simulated forced I_b and forced V_b data



BFP740F

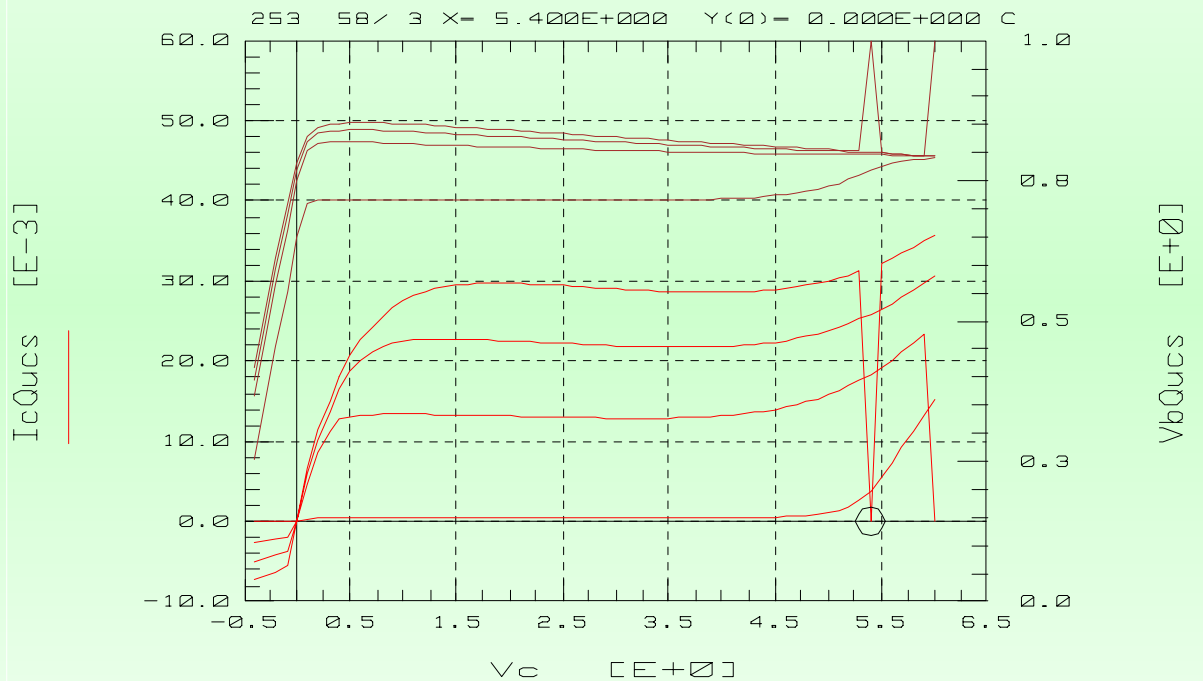
Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE0}	4	V
$T_A > 0^\circ\text{C}$		3.5	
$T_A \leq 0^\circ\text{C}$			
Collector-emitter voltage	V_{CES}	13	
Collector-base voltage	V_{CBO}	13	
Emitter-base voltage	V_{EBO}	1.2	
Collector current	I_C	30	mA
Base current	I_B	3	
Total power dissipation ¹⁾	P_{tot}	160	mW
$T_S \leq 90^\circ\text{C}$			
Junction temperature	T_j	150	$^\circ\text{C}$
Ambient temperature	T_A	-65 ... 150	



V_c from -0.4V to 6.0 V in 0.1 V steps

I_b from 1 μA to 121 μA in 40 μA steps

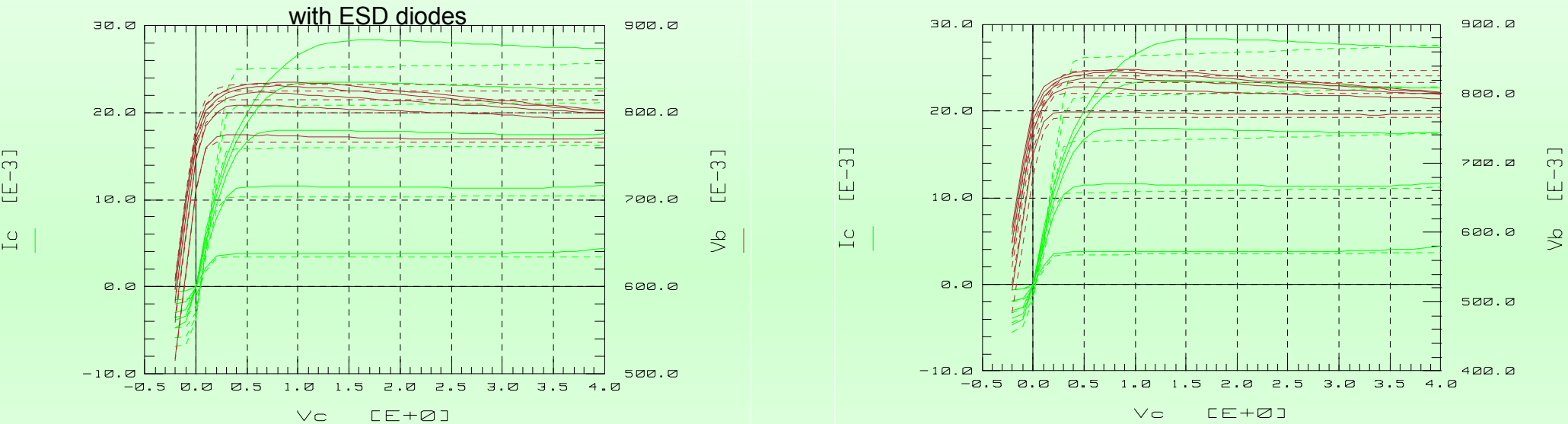


Housholder QR is the best converging solver

a mixture of avalanche and thermal effects causes convergency problems

the same problems occur in the latest QUCS 0.0.16 where four L0 models (1.12,1.2,1.2g,1.3) are implemented

I_b from 10 μA to 110 μA in 25 μA steps



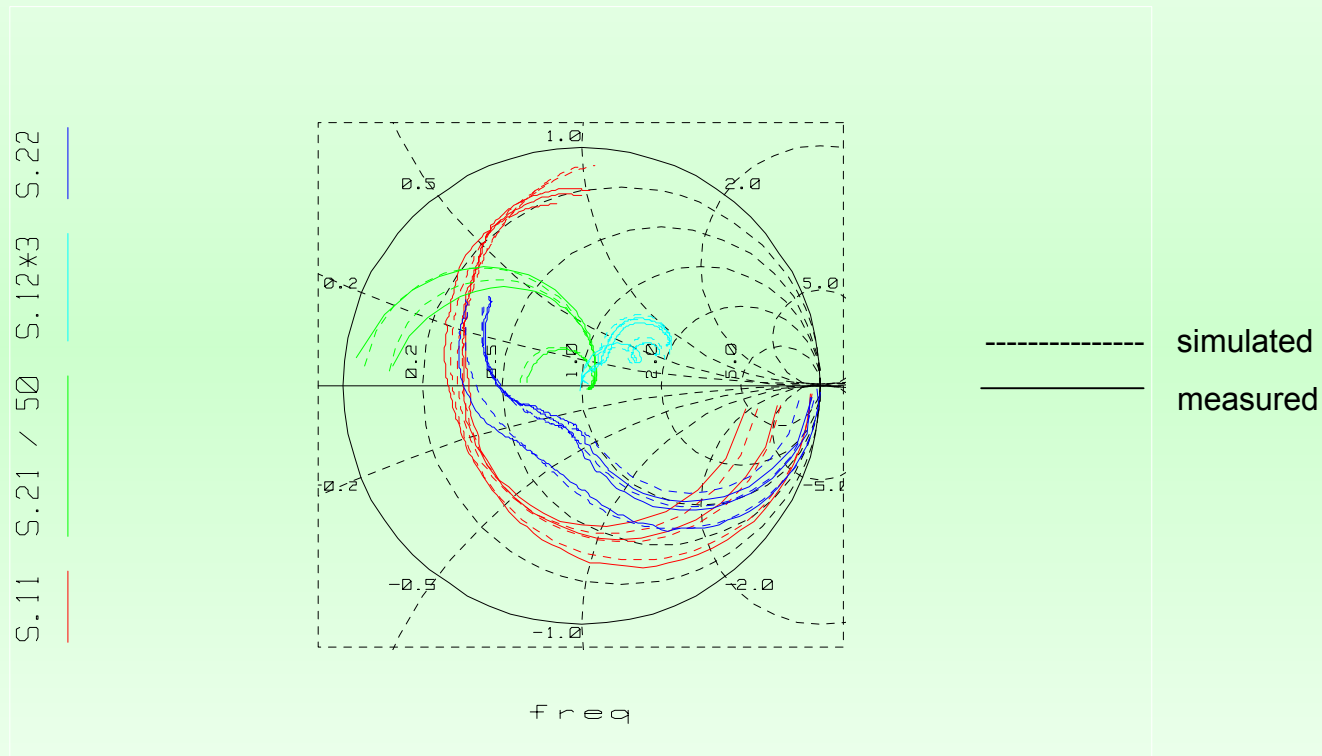
----- simulated
 _____ measured

well known problems with Gummel-Poon:

- no quasi-saturation
- no avalanche effect
- no self heating

S-parameter from 50 MHz to 14.05 GHz measured on FR4 Substrate with TRL/TRM calibration.

Operating Points: $V_c=2.0$ V, $I_{c_1}=3.8$ mA, $I_{c_2}=17.9$ mA, $I_{c_3}=28.3$ mA, $I_{b_1}=10$ μ A, $I_{b_2}=60$ μ A, $I_{b_3}=110$ μ A

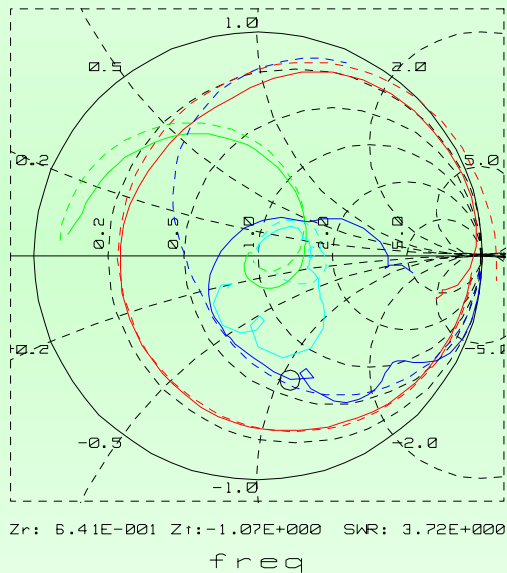


S-parameter supplied by Infineon from 100 MHz to 20 GHz measured substrate and calibration unknown.

Operating Point: $V_c=2.0$ V, $I_{c1}=4.0$ mA, valid up to 3 GHz for S12 and S22; Package model from Dec. 2008

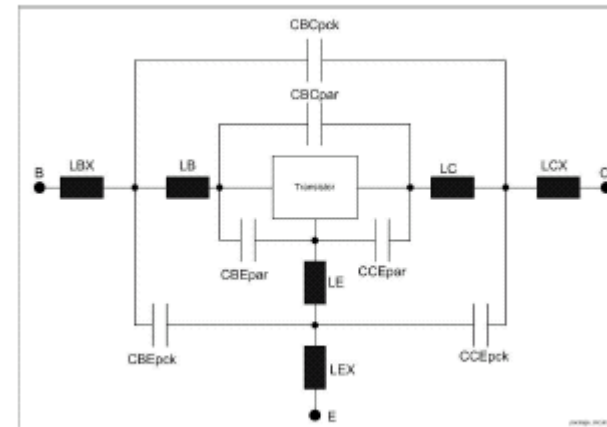
S.11 S.21 / 15 S.12x3 S.22

24 24 / 0 SW= 3.00E+009 SM(4)-M: 5.76E-001 P:-1.32E+000 M



----- simulated
 _____ measured

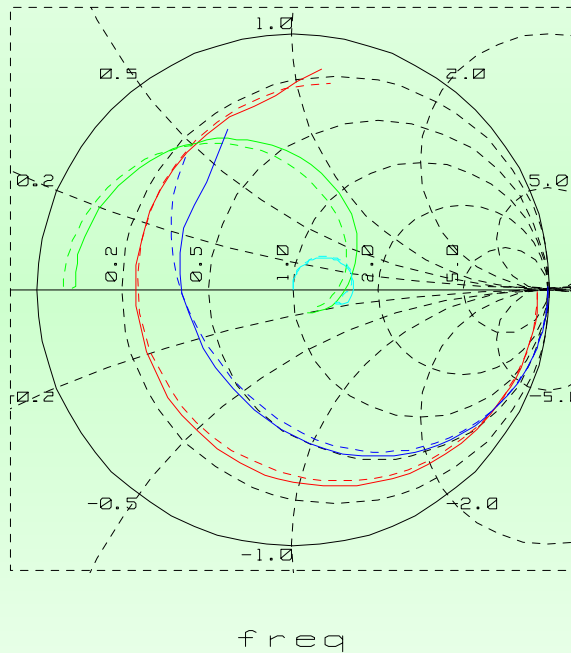
Package model



- L:Lbx 2 20 L=432.1p
- L:Lcx 1 10 L=679p
- L:Lex 0 30 L=105.2p
- C:Cbcpc 20 10 C=27.6f
- C:Ccepck 10 30 C=0.293f
- C:Cbecpk 20 30 C=97.62f
- L:Lb 20 22 L=628.7p
- L:Lc 10 11 L=0.137p
- L:Le 30 33 L=8.3p
- C:Cbepr 22 33 C=266.6f
- C:Cbcpr 22 11 C=60f
- C:Ccepr 11 33 C=123.4f

S-parameter supplied by Infineon from 10 MHz to 10 GHz measured substrate and calibration unknown.

Operating Point: $V_c=2.0$ V, $I_{c1}=4.0$ mA, valid up to 10 GHz with improved package model (June 2010)



----- simulated
 _____ measured

```

L:Lbx  2  20 L=432.1p
L:Lcx  1  10 L=679p
L:Lex  0  30 L=105.2p
C:Cbcpc 20 10 C=27.6f
C:Ccepck 10 30 C=0.293f
C:Cbcpc 20 30 C=97.62f
L:Lb  20 22 L=628.7p
L:Lc  10 11 L=0.137p
L:Le  30 33 L=8.3p
C:Cbepar 22 33 C=266.6f
C:Cbepar 22 11 C=60f
C:Ccepar 11 33 C=123.4f
R:R_Tr 44 4 R=307.5

D1:M_D1 33 25
D2:M_D2 4 25

R:RBLfdb 22 25 R=3.2
R:RPS 33 4 R=0.115215
R:RSUB 30 4 R=0.06119

D3:M_D3 4 15
D4:M_D4 23 33
D5:M_D5 23 15

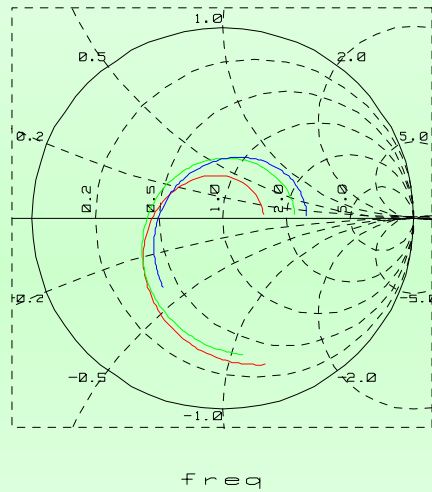
R:RLDNBL 15 11 R=14.8

BJTM2:X1 11 22 33 44

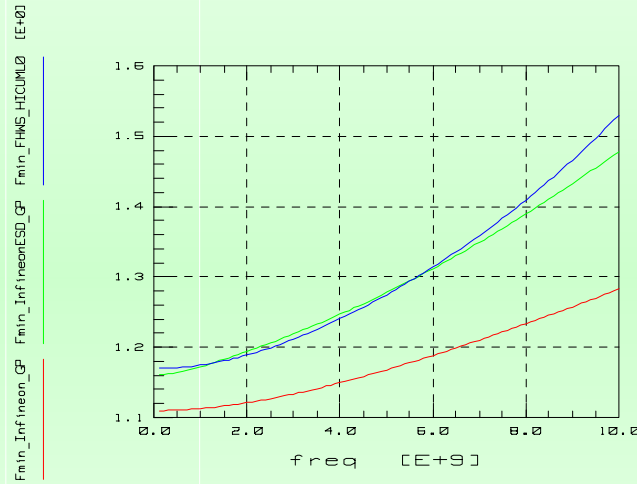
model D1 Diode Is=2.5E-017 N=1
Rs=6.1 Cjo=1E-014
model D2 Diode Is=2E-018 N=1
Rs=4170 Cjo=2.5E-014
model D3 Diode Is=3.5E-015
N=1.02 Rs=1380 Cjo=3E-014
model D4 Diode Is=3.5E-015 N=1
Rs=0.2 Cjo=3E-014
model D5 Diode Is=3.5E-015
N=1.02 Rs=4.7 Cjo=3E-014
    
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S.11 S.21 / 15 S.12x3 S.22

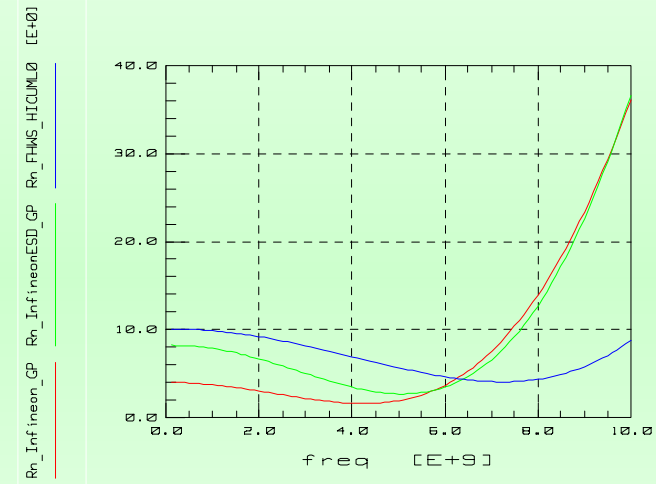
Sopt



Fmin



Rn / Ω



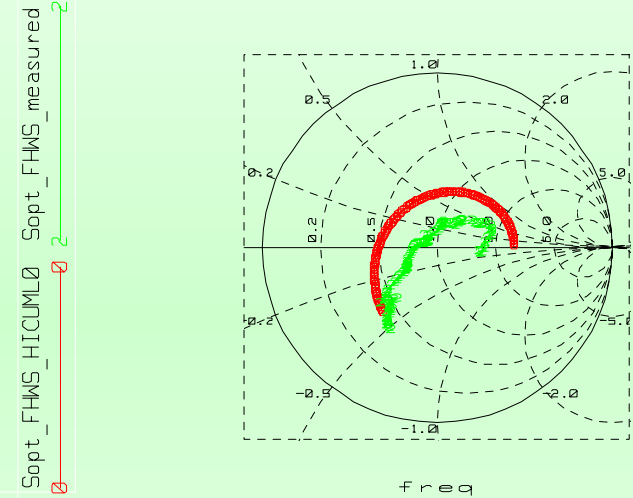
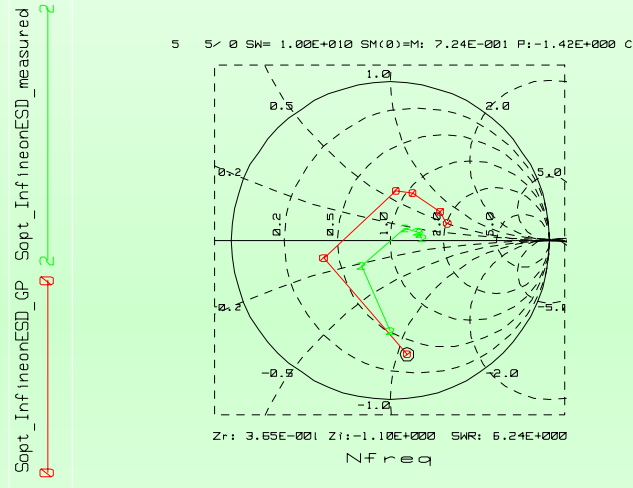
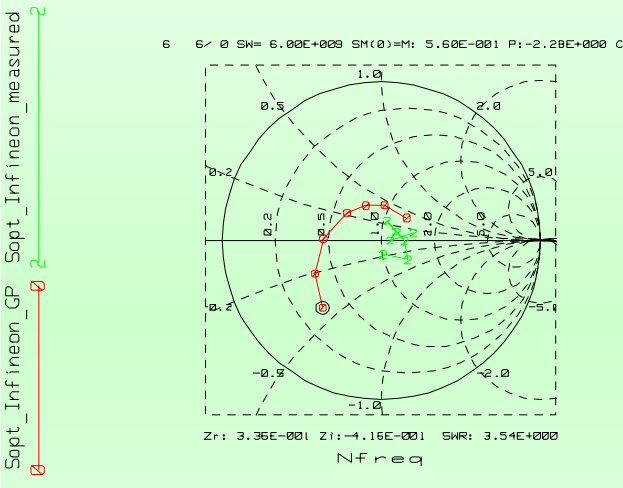
- Infineon GP
- Infineon ESD GP
- FHWS HICUM L0

Operating Point
Vc=2V, Ic=10 mA

Infineon 6GHz

Infineon ESD 10 GHz

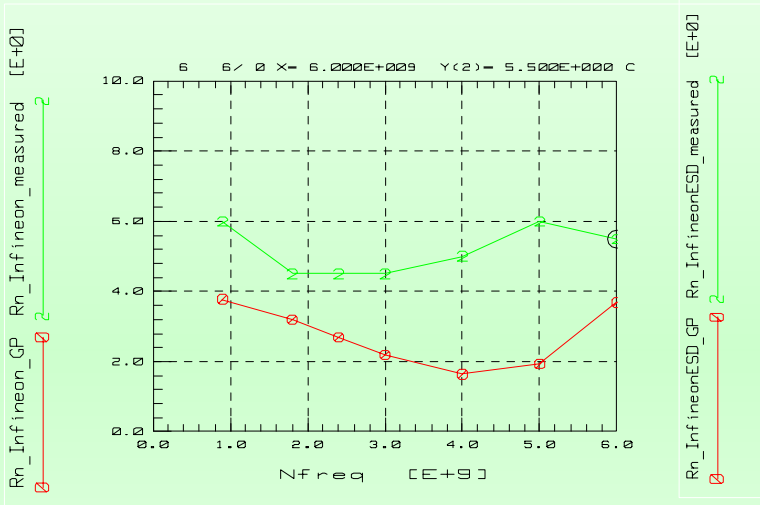
FHWS 10 GHz



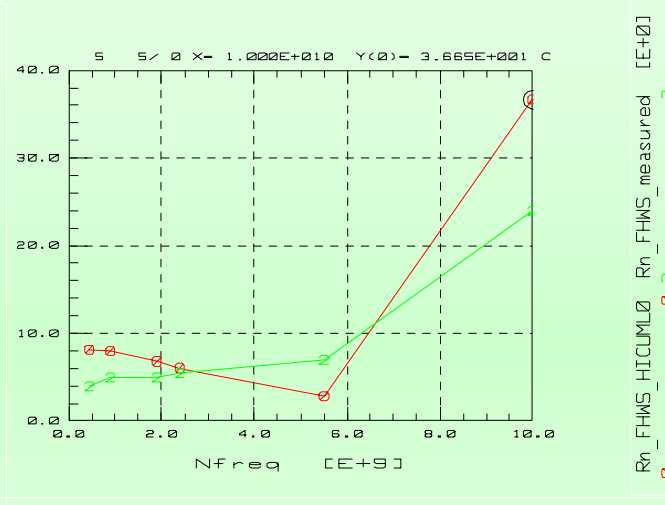
- simulated
- measured
- measured with deembedded LNA

operating point
Vc=2V, Ic=10 mA

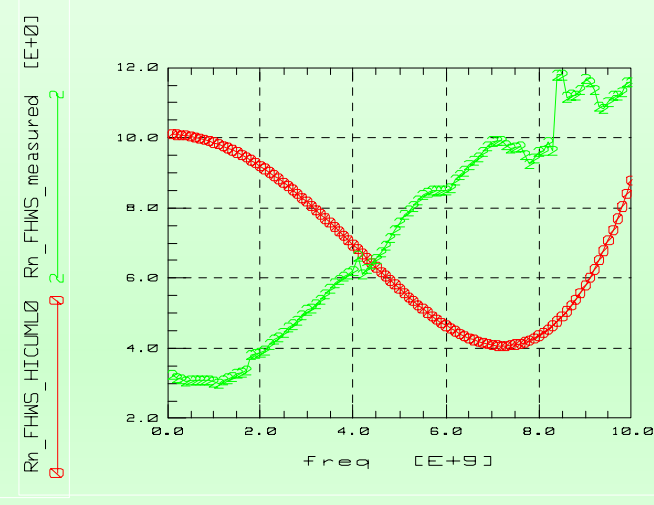
Infineon 6GHz



Infineon ESD 10 GHz



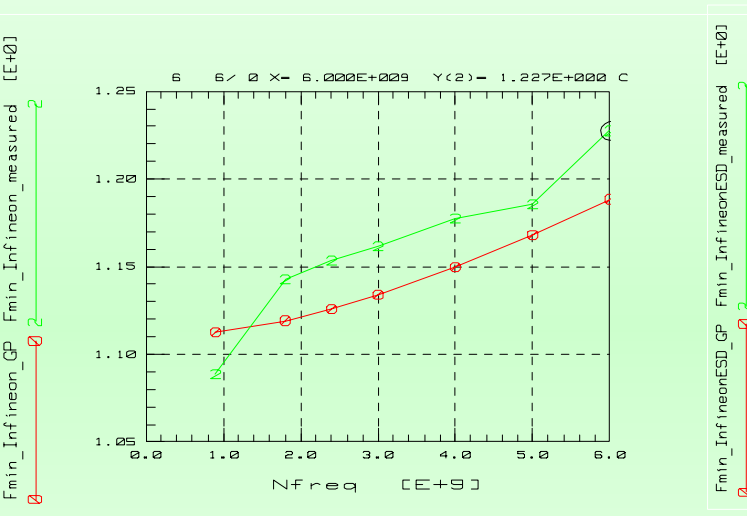
FHWS 10 GHz



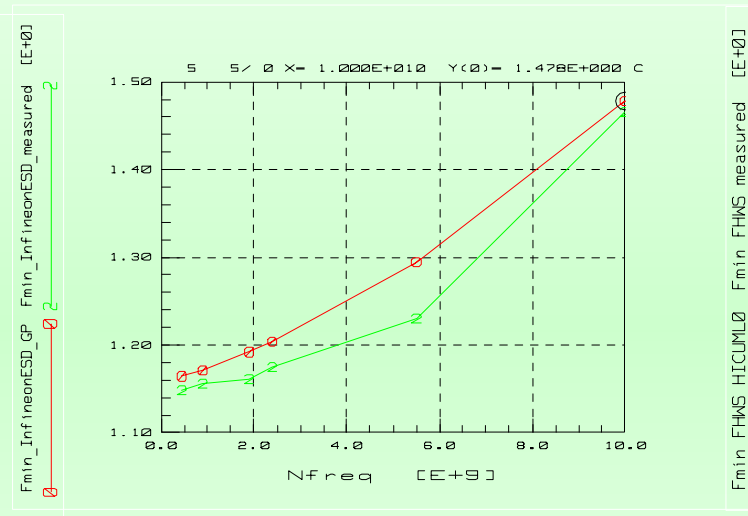
— simulated
— measured

operating point
Vc=2V, Ic=10 mA

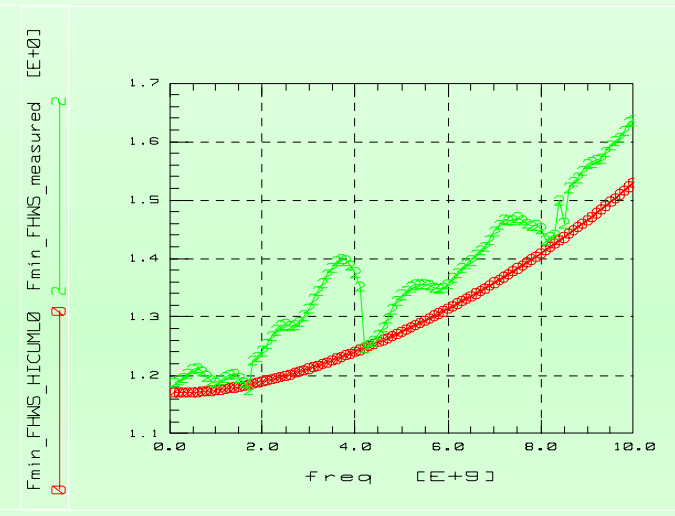
Infineon 6GHz



Infineon ESD 10 GHz



FHWS 10 GHz



— simulated
— measured

operating point
Vc=2V, Ic=10 mA

- two-pole thermal network is necessary for accurate simulation in SMD-transistors
- HICUML0 in Qucs can simulate DC and S-parameters with some convergency problems especially at operating points with avalanche and thermal interaction
- even Gummel-Ponn model is sufficient to simulate S-parameters with Noise if the package model is good
- for Noise data the question occurs what is more accurate: measurement or simulation ?
- will HICUM L0 be used in future by manufacturers for customer models?
- are there also convergency problems in the ic-design kit models with HICUML0?